

# Innovating Energy Technology

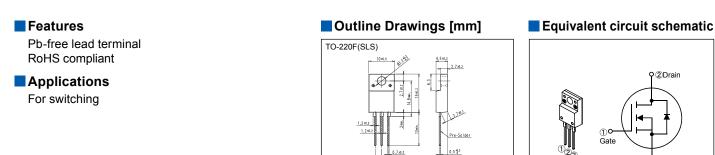
Q 2 Drain

③Source

http://www.fujielectric.com/products/semiconductor/ **FUJI POWER MOSFET** 

# Super J MOS<sup>®</sup> S1 series

# N-Channel enhancement mode power MOSFET



# Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Parameter	Symbol	Characteristics	Unit	Remarks
Drain Source Veltage	VDS	600	V	
Drain-Source Voltage	VDSX	600	V	V <sub>GS</sub> =-30V
Continuous Drain Current	lo Rat	130 ±30	А	Tc=25°C Note*1
		1613-11913月1	А	Tc=100°C Note*1
Pulsed Drain Current	lop	5 153 ±90 5 F	A	Note*1
Gate-Source Voltage	Ves	5 × ±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	Tar 2	diffet	А	Note *2
Non-Repetitive Maximum Avalanche Energy	Fince IPI	849.2 5 5 5 5 5	す。 mJ	Note *3
Maximum Drain-Source dV/dt	dVos/dt	5願し、50	∕kV/μs	V <sub>DS</sub> ≤ 600V
Peak Diode Recovery dV/dt			kV/µs	Note *4
Peak Diode Recovery - di/dt	-di/dt new ar	100	A/µs	Note *5
Maximum Bower Discinction tri目設計/CVG/th	en tor the	2.16	W	T <sub>a</sub> =25°C
Maximum Power Dissipation (注:新Man not USE th		90	vv	Tc=25°C
One reting and Stores Temperature Note: Do the	Tch	150	°C	
Operating and Storage remperature range	Tstg	-55 to +150	°C	
Maximum Power Dissipation Derating and Storage Temperature range Isolation Voltage	Viso	2	kVrms	t=60sec,f=60Hz

003

Gate
 Drain
 Source

Note \*1 : Limited by maximum channel temperature. Note \*2 : T<sub>ch</sub> ≤ 150°C, See Fig.1 and Fig.2 Note \*3 : Starting T<sub>ch</sub>=25°C, I<sub>As</sub>=4A, L=97.3mH, V<sub>DD</sub>=60V, R<sub>G</sub>=50Ω, See Fig.1 and Fig.2 EAs limited by maximum channel temperature and avalanche current.

Note \*4 :  $|F \le -I_D$ ,  $dI/dt=100A/\mu s$ ,  $V_{DS}$  peak  $\le 600V$ ,  $T_{ch} \le 150^{\circ}C$ . Note \*5 :  $|F \le -I_D$ ,  $dV/dt=30kV/\mu s$ ,  $V_{DS}$  peak  $\le 600V$ ,  $T_{ch} \le 150^{\circ}C$ .

#### Electrical Characteristics at T<sub>c</sub>=25°C (unless otherwise specified) Static Ratings

Parameter	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250μA V <sub>GS</sub> =0V		600	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	ID=1mA VDS=VGS		3	4	5	V
Zero Gate Voltage Drain Current	loss -	V <sub>DS</sub> =600V V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	-μA
		V <sub>DS</sub> =480V V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	150	-	
Gate-Source Leakage Current	IGSS	V <sub>GS</sub> = ± 30V V <sub>DS</sub> =0V		-	10	100	nA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	I <sub>D</sub> =15A V <sub>GS</sub> =10V		-	0.111	0.132	Ω
Gate resistance	RG	f=1MHz, open drain		-	3.3	-	Ω

### Dynamic Ratings

Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Forward Transconductance	<b>g</b> <sub>fs</sub>	I <sub>D</sub> =15A V <sub>DS</sub> =25V	11	23	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =400V	-	2080	-	
Output Capacitance	Coss	V <sub>GS</sub> =0V	-	60	-	
Reverse Transfer Capacitance	Crss	f=250kHz	-	4	-	
Effective output capacitance, energy related (Note *6)	C <sub>o(er)</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =0400V	-	160	-	pF
Effective output capacitance, time related (Note *7)	C <sub>o(tr)</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =0400V ID=constant	-	535	-	
Turn-On Time	t <sub>d(on)</sub>		-	119	-	
Turn-On Time	tr	Vpp=400V, Vcs=10V Ib=15A, Rc=27Ω See Fig.3 and Fig.4	-	32	-	ns
Turne Off Times	t <sub>d(off)</sub>		-	186	-	
Turn-Off Time	tr		-	22	-	
Total Gate Charge	Q <sub>G</sub>		-	73	-	
Gate-Source Charge	Q <sub>GS</sub>	$V_{DD}$ =400V, I <sub>D</sub> =30A	-	22	-	1
Gate-Drain Charge	Q <sub>GD</sub>	− V <sub>GS</sub> =10V _ See Fig.5	-	29	-	nC
Drain-Source crossover Charge	Qsw		-	11.5	-	1

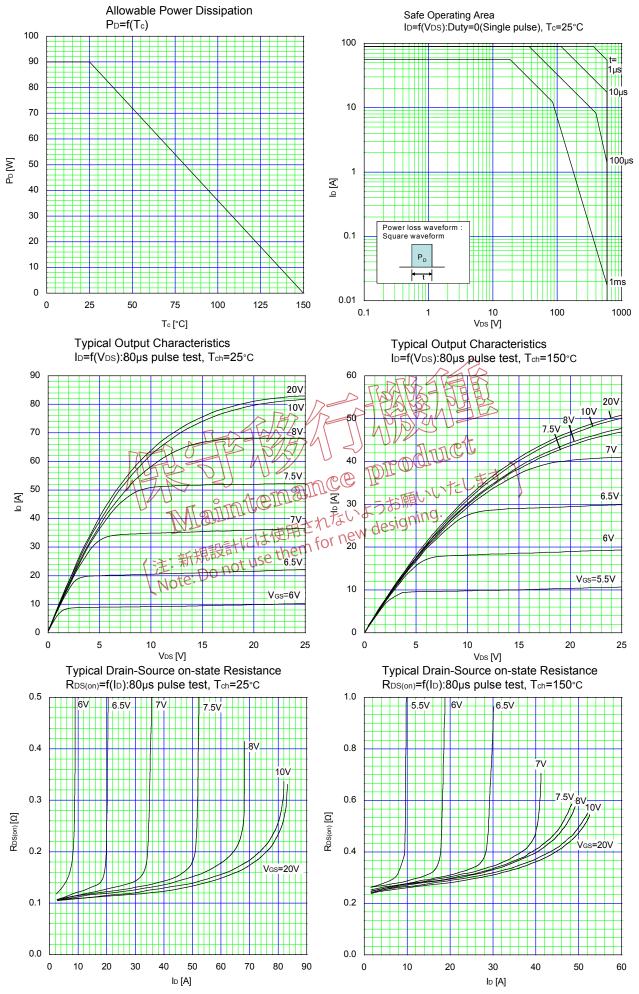
Note \*6 :  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V. Note \*7 :  $C_{o(tr)}$  is a fixed capacitance that gives the same charging times as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V.

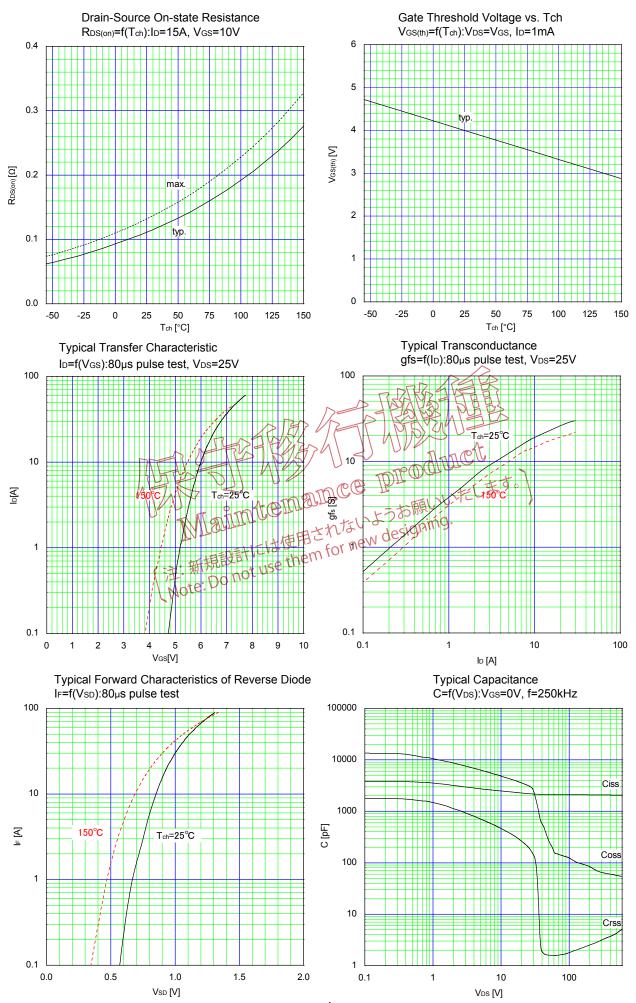
## Reverse Diode

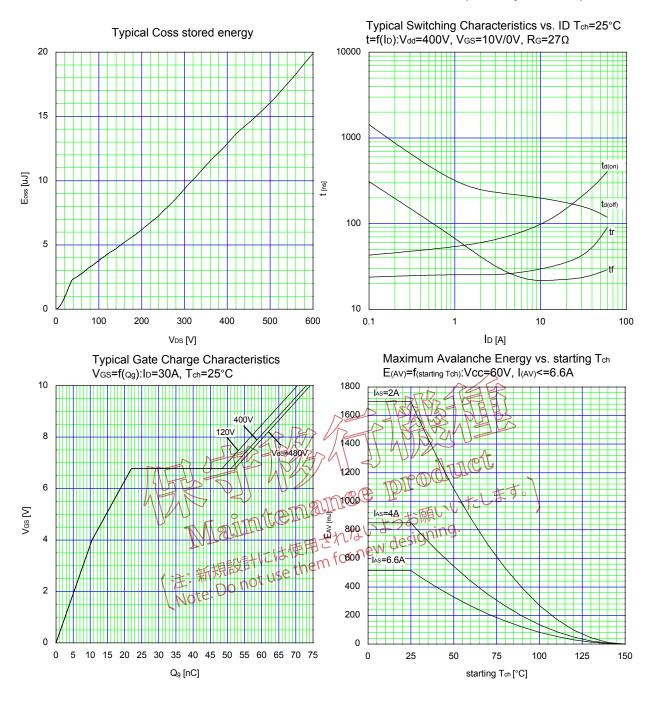
Parameter	Symbol	Conditions	e min 4	typ.	max.	Unit
Avalanche Capability	IAV AR	L=24.7mH, To=25°C See Fig. 7 and Fig.2	6.6	-	-	А
Diode Forward On-Voltage	Too S	It=30A.Ves=0V Ten=25°C	dhuice	≠ <b>d</b> . \	1.35	V
Reverse Recovery Time		The 25 CO DE LA CE DE CE Tenezo Constant Tenezo Consta	UNITED	180	-	ns
Reverse Recovery Charge	Q. VILat	-di/dt=100A/us T==25(g)使用されない design	- 119	1.2	-	μC
Peak Reverse Recovery Current	泄.新規語	not USE the ligit of	-	13.5	-	А

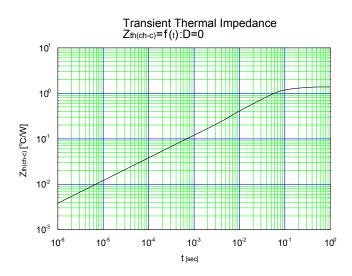
## Thermal Resistance

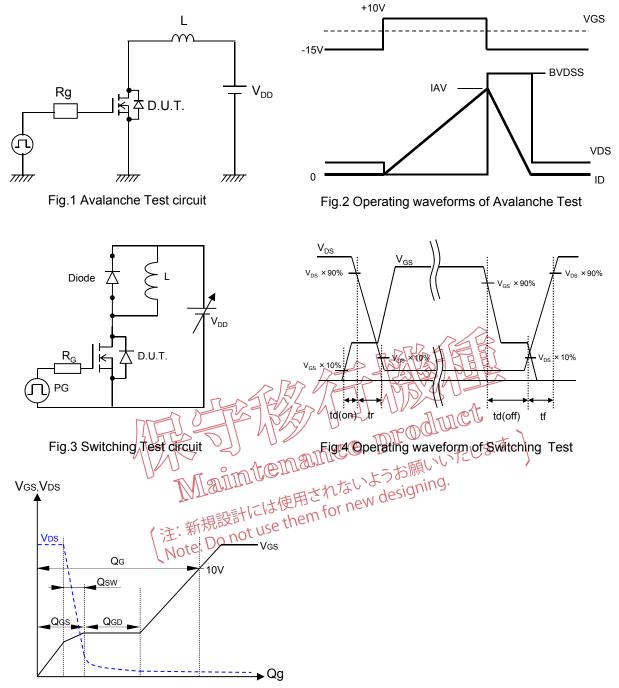
Parameter	Symbol	min.	typ.	max.	Unit
Channel to Case	Rth(ch-c)	-	-	1.39	°C/W
Channel to Ambient	Rth(ch-a)	-	-	58	°C/W



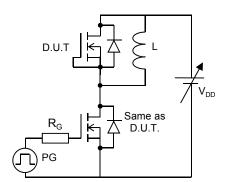












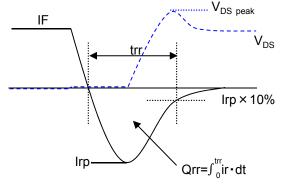
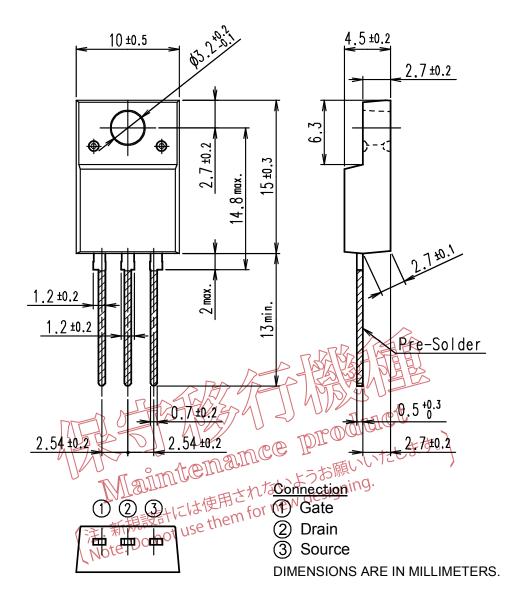


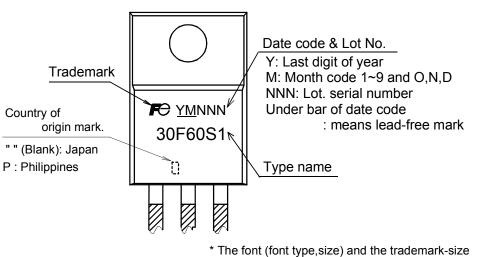
Fig.6 Reverse recovery Test circuit

Fig.7 Operating waveform of Reverse recovery Test

## Outview: TO-220F(SLS) Package



Marking



might be actually different.

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